RFW

## THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Chuen Rong Leu et al.

Assignee:

Bridge Semiconductor Corporation

Title:

METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR

Serial No.:

10/719,823

Filed:

November 21, 2003

Examiner:

Unknown

Group Art Unit:

2812

Atty. Docket No.:

BDG024-1

COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, VA 22313-1450

## REQUEST FOR CORRECTED FILING RECEIPT

Attached is a copy of the official filing receipt received from the Patent and Trademark Office in the captioned-application for which a corrected filing receipt is respectfully requested.

The Title should be "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR" (rather than "SEMICONDUCTOR CHIP ASSEMBLY WITH EMBEDDED METAL PILLAR") as set forth in the Transmittal and the Preliminary Amendment.

The correction is noted in red ink on the attached copy of the filing receipt.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on April-26, 2006.

A , 26, 06

Date of Signature

David M. Sigmond Attorney for Applicant

Respectfully submitted,

David M. Sigmond Attorney for Applicant Reg. No. 34,013 (303) 554-8371 (303) 554-8667 (fax)





UNITED STATES DEPARTMENT OF COMMERCE United States Pattern and Trademark Office Address COMMISSIONER FOR PATENTS P.O. Box 1450 Alexadria, Vignia 22313-1450 www.mpto.gov

FILING OR 371 IND CLMS TOT CLMS ATTY.DOCKET NO DRAWINGS FIL FEE REC'D ART UNIT APPL NO. (c) DATE 11 36 200 BDG024-1 2349 10/719.823 11/21/2003 2812

**CONFIRMATION NO. 2973** 

David M. Sigmond 2440 Andrew Drive Superior, CO 80027

FILING RECEIPT \*OC000000011945414\*

Date Mailed: 02/23/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

### Applicant(s)

Chuen-Rong Leu, Hsinchu, TAIWAN; Charles W.C. Lin, Singapore, SINGAPORE;

#### Domestic Priority data as claimed by applicant

This application is a CON of 10/714,794 11/17/2003 which is a CIP of 10/235,331 09/05/2002 PAT 6,653,742 which is a DIV of 09/939,140 08/24/2001 PAT 6,576,539 which is a CIP of 09/878,626 06/11/2001 PAT 6,653,217 which is a CIP of 09/687,619 10/13/2000 PAT 6,440,835 and said 10/714,794 11/17/2003 claims benefit of 60/509,299 10/07/2003 and claims benefit of 60/507,145 09/30/2003

#### Foreign Applications

If Required, Foreign Filing License Granted: 02/20/2004

Projected Publication Date: Request for Non-Publication Acknowledged

Non-Publication Request: Yes

Early Publication Request: No

\*\* SMALL ENTITY \*\*

Title Method of making a

Semiconductor chip assembly with embedded metal pillar

Preliminary Class

438

# LICENSE FOR FOREIGN FILING UNDER Title 35, United States Code, Section 184 Title 37, Code of Federal Regulations, 5.11 & 5.15

### **GRANTED**

The applicant has been granted a license under 35 U.S.C. 184, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" followed by a date appears on this form. Such licenses are issued in all applications where the conditions for issuance of a license have been met, regardless of whether or not a license may be required as set forth in 37 CFR 5.15. The scope and limitations of this license are set forth in 37 CFR 5.15(a) unless an earlier license has been issued under 37 CFR 5.15(b). The license is subject to revocation upon written notification. The date indicated is the effective date of the license, unless an earlier license of similar scope has been granted under 37 CFR 5.13 or 5.14.

This license is to be retained by the licensee and may be used at any time on or after the effective date thereof unless it is revoked. This license is automatically transferred to any related applications(s) filed under 37 CFR 1.53(d). This license is not retroactive.

The grant of a license does not in any way lessen the responsibility of a licensee for the security of the subject matter as imposed by any Government contract or the provisions of existing laws relating to espionage and the national security or the export of technical data. Licensees should apprise themselves of current regulations especially with respect to certain countries, of other agencies, particularly the Office of Defense Trade Controls, Department of State (with respect to Arms, Munitions and Implements of War (22 CFR 121-128)); the Office of Export Administration, Department of Commerce (15 CFR 370.10 (j)); the Office of Foreign Assets Control, Department of Treasury (31 CFR Parts 500+) and the Department of Energy.

#### **NOT GRANTED**

No license under 35 U.S.C. 184 has been granted at this time, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" DOES NOT appear on this form. Applicant may still petition for a license under 37 CFR 5.12, if a license is desired before the expiration of 6 months from the filing date of the application. If 6 months has lapsed from the filing date of this application and the licensee has not received any indication of a secrecy order under 35 U.S.C. 181, the licensee may foreign file the application pursuant to 37 CFR 5.15(b).